

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3538581

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHAN MOO PARK	09/22/2015
TAE GON KANG	09/22/2015
YOO JIN JUNG	09/22/2015
JONG CHEOL LIM	09/22/2015
SANG HYUN HONG	09/22/2015
RECEIVING PARTY DATA	
Name:	SAMSUNG SDI CO., LTD.
Street Address:	150-20 GONGSE-RO
Internal Address:	GIHEUNG-GU
City:	YONGIN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	446-902
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14862467
CORRESPONDENCE DATA	
Fax Number:	(704)945-6735
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	704-945-6700
Email:	docket@ahpapatent.com
Correspondent Name:	MELISSA B. PENDLETON
Address Line 1:	11610 N. COMMUNITY HOUSE ROAD
Address Line 2:	SUITE 200
Address Line 4:	CHARLOTTE, NORTH CAROLINA 28277
ATTORNEY DOCKET NUMBER:	1224.196
NAME OF SUBMITTER:	MELISSA B. PENDLETON
SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	09/23/2015

Total Attachments: 4

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RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)
 CHAN MOO PARK
 TAE GON KANG
 YOO JIN JUNG
 JONG CHEOL LIM
 SANG HYUN HONG
 Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: Samsung SDI Co., Ltd.
 Internal Address: _____

3. Nature of conveyance/Execution Date(s):
 Execution Date(s) September 22, 2015
 Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

Street Address: 150-20, Gongse-ro, Giheung-gu

 City: Yongin-si
 State: Gyeonggi-do
 Country: South Korea Zip: _____
 Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s): This document is being filed together with a new application.
 A. Patent Application No.(s)
14/862,467
 Additional numbers attached? Yes No

B. Patent No.(s)

5. Name and address to whom correspondence concerning document should be mailed:
 Name: Additon, Higgins & Pendleton, P.A.
 Internal Address: _____

 Street Address: 11610 N. Community House Road, Suite 200
 City: Charlotte
 State: NC Zip: 28277-2199
 Phone Number: 704-945-6700
 Fax Number: 704-945-6735
 Email Address: _____

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information
 a. Credit Card Last 4 Numbers _____
 Expiration Date _____
 b. Deposit Account Number _____
 Authorized User Name _____

9. Signature: /Melissa B. Pendleton/ September 23, 2015

 Signature Date
Melissa B. Pendleton

 Name of Person Signing
 Total number of pages including cover sheet, attachments, and documents: 4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1460, Alexandria, V.A. 22313-1460

COMBINED DECLARATION AND ASSIGNMENT

WHEREAS, I, Chan Moo PARK, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Tae Gon KANG, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Yoo Jin JUNG, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Jong Cheol LIM, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and Sang Hyun HONG, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition and Molded Article Using the Same*, for which an application for United States Letters Patent is being filed concurrently herewith which application claims priority from a Korean application filed on September 30, 2014, under Serial No. 10-2014-0131327, and a Korean application filed on August 21, 2015, under Serial No. 10-2015-0118246, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-902, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE,

its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

Sep. 22, 2015 Chan Moo Park
Chan Moo PARK

Sep. 22, 2015 Tae Gon Kang
Tae Gon KANG

Sep. 22, 2015 Yoo Jin JUNG
Yoo Jin JUNG

Sep. 22, 2015 Jong Cheol Lim
Jong Cheol LIM

Sep. 22, 2015 Sang Hyun Hong
Sang Hyun HONG